

**ABSTRACT**

The invention provides a dicing and die bonding pressure-sensitive adhesive sheet having a pressure-sensitive adhesive layer that exhibits excellent embedding properties in die bonding and thereby can prevent formation of voids between die pads and the pressure-sensitive adhesive layer even when chips are mounted on the die pads having great difference of height.

The dicing and die bonding pressure-sensitive adhesive sheet comprises a base material and a pressure-sensitive adhesive layer disposed thereon, the pressure-sensitive adhesive layer having a ratio ( $M_{100}/M_{70}$ ) of a modulus of elasticity at 100°C ( $M_{100}$ ) to a modulus of elasticity at 70°C ( $M_{70}$ ) being 0.5 or less.